

REMARKS/ARGUMENTS

Applicants would like to thank the Examiner for the careful consideration given the present application. The application has been carefully reviewed in light of the Office Action. Favorable reconsideration of the application is requested in view of the remarks and amendments made herein.

Claims 1–4 and 11 were rejected under 35 U.S.C. 102(e) as being anticipated by Kurosawa (U.S. Patent No. 6,709,543). Traversal of this rejection is made for at least the following reasons. Kurosawa does not disclose vacuum-sucking step in which a semiconductor chip adhered to a sheet is bent and deformed *by a vacuum suction force* in an almost same bent shape in a continuous bent range from an outer peripheral portion of one side of the chip to an outer peripheral portion of another one side of the chip thereby to exfoliate the sheet from a lower surface of the semiconductor chip, as required by independent claims 1 and 11. As indicated by the Examiner, Figs. 19A, 20A, 21A and col. 17, lines 13–27 and 35–45 disclose a semiconductor chip 1 that is bent. However, the semiconductor chip 1 of Kurosawa is bent via a plurality of thrust pins 24 and not by a vacuum suction force, as required by claims 1 and 11. Any vacuum suction force disclosed in the Kurosawa patent only discloses that the vacuum suction force acts on the adhesive sheet. There is nothing that discloses, teaches, or suggests that the vacuum suction force of Kurosawa acts on the semiconductor chip 1 such that the semiconductor chip 1 is bent.

Further, Kurosawa fails to disclose *abutting a suction surface* of a sheet exfoliation mechanism *against a lower surface of the sheet*, as required by claims 1 and 11. In Kurosawa, the thrust pins 24 abut the adhesive sheet 22. While a vacuum suction can be provided between

the individual thrust pins 24, the thrust pins 24 themselves cannot be considered a suction surface.

Because Kurosawa does not disclose each and every limitation set forth in independent claim 1 and 11, Kurosawa cannot anticipate such claims. Withdrawal of this rejection and allowance of claims 1–4 and 11 are respectfully requested.

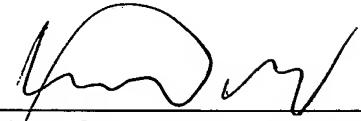
Claims 5–10 were rejected under 35 U.S.C. 103(a) as being unpatentable over Akira (JP 2001-118862) in view of Kurosawa (U.S. Patent No. 6,709,543). Traversal of this rejection is made for at least the following reasons. Neither Akira nor Kurosawa, alone or in combination, teach or suggest that air is vacuum-sucked from suction grooves to bend and deform a semiconductor chip adhered to a sheet together with the sheet thereby to exfoliate the sheet from a lower surface of the semiconductor chip due to the bend deformation, as recited in independent claims 5 and 10. The Examiner concedes that Akira fails to show that the semiconductor chip is bent and thus relies on Kurosawa in an attempt to make up for the deficiencies of Akira. However, Kurosawa fails to disclose, teach, or suggest that air is vacuum sucked to bend and deform a semiconductor chip adhered to a sheet. Rather, Kurosawa only discloses that a semiconductor chip is bent due to movement of a plurality of thrust pins provided against a bottom surface of the adhesive sheet. The vacuum suction disclosed in Kurosawa only bends and deforms the adhesive sheet, not the actual semiconductor chip, as required by the subject claims.

In light of the foregoing, it is respectfully submitted that the present application is in a condition for allowance and notice to that effect is hereby requested. If it is determined that the application is not in a condition for allowance, the Examiner is invited to initiate a telephone interview with the undersigned attorney to expedite prosecution of the present application.

Appln. No. 10/620,184
Amdt. dated September 18, 2006
Reply to Office Action dated June 30, 2006

If there are any additional fees resulting from this communication, please charge same to
our Deposit Account No. 16-0820, our Order No. 35857.

Respectfully submitted,
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